ASSP

Dual Serial Input PLL Frequency Synthesizer

MB15F74UV

■ DESCRIPTION

The Fujitsu MB15F74UV is a serial input Phase Locked Loop (PLL) frequency synthesizer with a 4000 MHz and a 2000 MHz prescalers. A 64/65 or a 128/129 for the 4000 MHz prescaler, and a 32/33 or a 64/65 for the 2000 MHz prescaler can be selected for the prescaler that enables pulse swallow operation.

The BiCMOS process is used, as a result a supply current is typically 9.0 mA at 3.0 V. The supply voltage range is from 2.7 V to 3.6 V. A refined charge pump supplies well-balanced output current with 1.5 mA and 6 mA selectable by serial date. The serial data format is the same as MB15F74UL. Fast locking is achieved for adopting the new circuit.

MB15F74UV is in the small package (BCC18) which decreases a mount area of MB15F74UV about 50% comparing with the former BCC20 (for dual PLL) .

■ FEATURES

• High frequency operation : RF synthesizer : 4000 MHz Max

: IF synthesizer : 2000 MHz Max

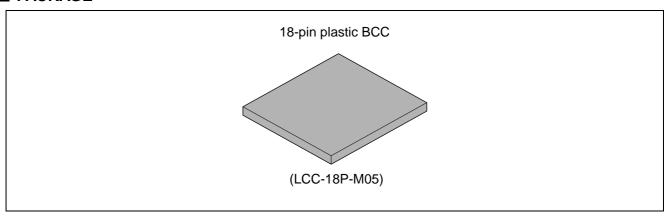
• Low power supply voltage : Vcc = 2.7 V to 3.6 V

Ultra low power supply current : Icc = 9.0 mA Typ

(Vcc = 3.0 V, Ta = +25 °C, $SW_{IF} = SW_{RF} = 0$ in IF/RF locking state)

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■ PACKAGE





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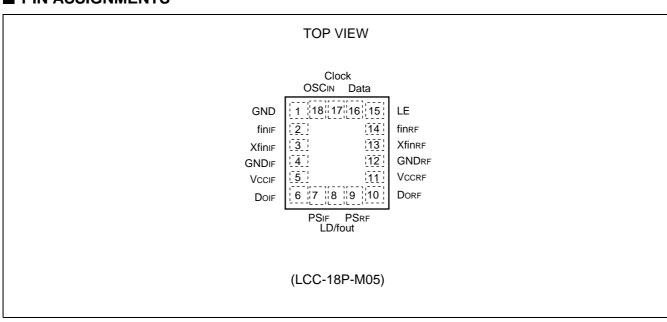
• Direct power saving function : Power supply current in power saving mode

Typ 0.1
$$\mu$$
A (Vcc = 3.0 V, Ta = +25 °C at 1 system)

Max 10 μ A (Vcc = 3.0 V at 1 system)

- Software selectable charge pump current : 1.5 mA/6.0 mA Typ
- Dual modulus prescaler: 4000 MHz prescaler (64/65 or128/129) /2000 MHz prescaler (32/33 or 64/65)
- 23 bit shift register
- Serial input binary 14-bit programmable reference divider : R = 3 to 16,383
- Serial input programmable divider consisting of:
 - Binary 7-bit swallow counter: 0 to 127
 - Binary 11-bit programmable counter: 3 to 2,047
- Built-in high-speed tuning, low-noise phase comparator, current-switching type constant current circuit
- On-chip phase control for phase comparator
- On-chip phase comparator for fast lock and low noise
- Built-in digital locking detector circuit to detect PLL locking and unlocking
- Operating temperature : Ta = $-40 \, ^{\circ}\text{C}$ to $+85 \, ^{\circ}\text{C}$
- Serial data format compatible with MB15F74UL
- Ultra small package BCC18 (2.4 mm × 2.7 mm × 0.45 mm)

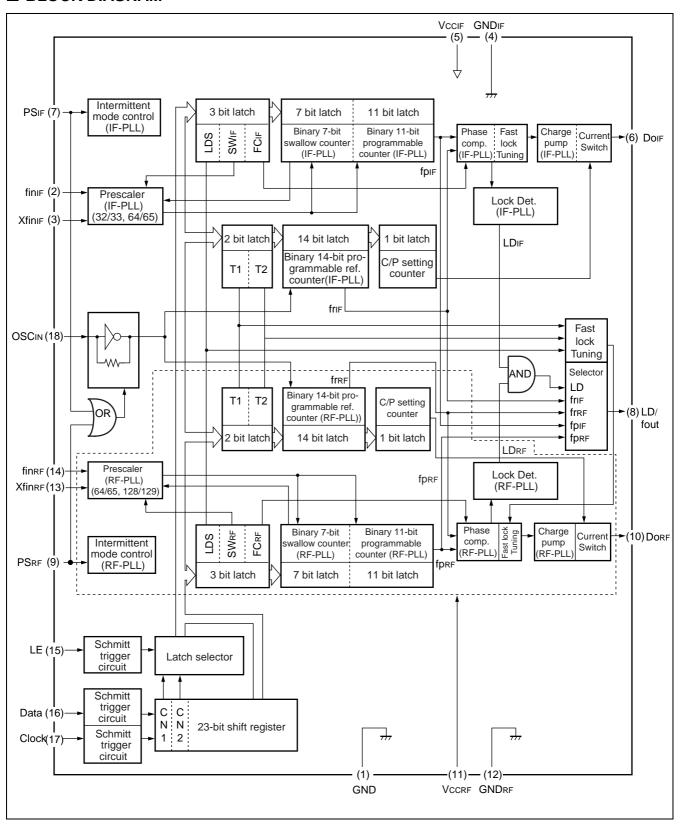
■ PIN ASSIGNMENTS



■ PIN DESCRIPTION

Pin no.	Pin name	I/O	Descriptions
1	GND	_	Ground pin for OSC input buffer and the shift register circuit.
2	finıғ	I	Prescaler input pin for the IF-PLL. Connection to an external VCO should be AC coupling.
3	XfinıF	I	Prescaler complimentary input for the IF-PLL section. This pin should be grounded via a capacitor.
4	GND _{IF}	_	Ground pin for the IF-PLL section.
5	Vccif	_	Power supply voltage input pin for the IF-PLL section, the shift register and the oscillator input buffer.
6	Doir	0	Charge pump output for the IF-PLL section.
7	PSıF	I	Power saving mode control pin for the IF-PLL section. This pin must be set at "L" when the power supply is started up. (Open is prohibited.) $PS_{IF} = "H"$; Normal mode/ $PS_{IF} = "L"$; Power saving mode
8	LD/fout	0	Lock detect signal output (LD) /phase comparator monitoring output (fout) pin. The output signal is selected by LDS bit in a serial data. LDS bit = "H"; outputs fout signal/LDS bit = "L"; outputs LD signal
9	PS _{RF}	I	Power saving mode control for the RF-PLL section. This pin must be set at "L" when the power supply is started up. (Open is prohibited.) PSRF = "H"; Normal mode/PSRF = "L"; Power saving mode
10	Dorf	0	Charge pump output for the RF-PLL section.
11	Vccrf		Power supply voltage input pin for the RF-PLL section.
12	GNDrf		Ground pin for the RF-PLL section
13	Xfin _{RF}	I	Prescaler complimentary input pin for the RF-PLL section. This pin should be grounded via a capacitor.
14	fin _{RF}	I	Prescaler input pin for the RF-PLL. Connection to an external VCO should be via AC coupling.
15	LE	I	Load enable signal input pin (with the schmitt trigger circuit) When LE is set "H", data in the shift register is transferred to the corresponding latch according to the control bit in a serial data.
16	Data	I	Serial data input pin (with the schmitt trigger circuit) Data is transferred to the corresponding latch (IF-ref. counter, IF-prog. counter, RF-ref. counter, RF-prog. counter) according to the control bit in a serial data.
17	Clock	I	Clock input pin for the 23-bit shift register (with the schmitt trigger circuit) One bit data is shifted into the shift register on a rising edge of the clock.
18	OSCIN	I	The programmable reference divider input pin. TCXO should be connected with an AC coupling capacitor.

■ BLOCK DIAGRAM



■ ABSOLUTE MAXIMUM RATINGS

Doromot	~=	Symbol	Rat	ting	l lmi4
Paramet	er	Symbol	Min	Max	Unit
Power supply voltage		Vcc	-0.5	4.0	V
Input voltage		Vı	-0.5	Vcc + 0.5	V
Output voltage	LD/fout	Vo	GND	Vcc	V
Output voltage	Doif, Dorf	V _{DO}	GND	Vcc	V
Storage temperature		Tstg	-55	+125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol		Value		Unit	Domorko
raiailletei	Symbol	Min	Тур	Max	Oilit	Remarks Vccrf = Vccif
Power supply voltage	Vcc	2.7	3.0	3.6	V	Vccrf = Vccif
Input voltage	Vı	GND	_	Vcc	V	
Operating temperature	Та	-40	_	+85	°C	

Note: • Vccrf and Vccif must supply equal voltage.

Even if either RF-PLL or IF-PLL is not used, power must be supplied to VccrF and VccrF to keep them equal.

It is recommended that the non-use PLL is controlled by power saving function.

- Although this device contains an anti-static element to prevent electrostatic breakdown and the circuitry has been improved in electrostatic protection, observe the following precautions when handling the device.
 - When storing and transporting the device, put it in a conductive case.
 - Before handling the device, confirm the (jigs and) tools to be used have been uncharged (grounded) as well as yourself. Use a conductive sheet on working bench.
 - Before fitting the device into or removing it from the socket, turn the power supply off.
 - When handling (such as transporting) the device mounted board, protect the leads with a conductive sheet.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

> No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

 $(Vcc = 2.7 \text{ V to } 3.6 \text{ V}, Ta = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$

_					2.7 V to 3	Value		,
Parameter		Symbol	Condi	tion	Min	Тур	Max	Unit
Dower cumply current		CCIF *1	fin _{IF} = 2000 MHz V _{CCIF} = 3.0 V		2.1	2.5	3.2	mA
Power supply current		CCRF *1	finrf = 2500 MHz Vccrf = 3.0 V		5.7	6.5	8.4	mA
Power saving current		PSIF	PS _{IF} = PS _{RF} = "L"		_	0.1 *2	10	μΑ
Power saving current		IPSRF	PS _{IF} = PS _{RF} = "L"	_	0.1 *2	10	μΑ	
fin _{IF} *3		fin⊫	IF PLL		200	_	2000	MHz
Operating frequency	finrf *3	fin _{RF}	RF PLL		2000	_	4000	MHz
	OSCIN	fosc	_		3		40	MHz
lancet a analticité	fin⊫	Pfin⊩	IF PLL, 50 Ω sys	tem	-15		+2	dBm
Input sensitivity	fin _{RF}	Pfinre	RF PLL, 50 Ω system		-10	_	+2	dBm
Input available voltage	OSCIN	Vosc	_		0.5	1.0	1.5	V _{P-P}
"H" level input voltage	Data LE	VIH	Schmitt trigger in	0.7 Vcc + 0.4	_	_	V	
"L" level input voltage	Clock	VIL	Schmitt trigger in	_	_	0.3 Vcc - 0.4	V	
"H" level input voltage	PS⊮	ViH	_	0.7 Vcc	_	_	V	
"L" level input voltage	PSRF	VIL	_		_	_	0.3 Vcc	V
"H" level input current	Data LE	I _{IH} *4	_		-1.0		+1.0	μΑ
"L" level input current	Clock PS	l ı∟* ⁴	_		-1.0	_	+1.0	μΑ
"H" level output voltage	LD/	Vон	Vcc = 3.0 V, Iон =	-1 mA	Vcc - 0.4	_	_	V
"L" level output voltage	fout	Vol	Vcc = 3.0 V, IoL =	1 mA		_	0.4	V
"H" level output voltage	Doir	V _{DOH}	Vcc = 3.0 V, Ірон :	= -0.5 mA	Vcc - 0.4	_	_	V
"L" level output voltage	Dorf	VDOL	Vcc = 3.0 V, IDOL =	= 0.5 mA	_	_	0.4	V
High impedance cutoff current	Doif Dorf	loff	Vcc = 3.0 V Voff = 0.5 V to Vc	cc – 0.5 V	_	_	2.5	nA
"H" level output current	LD/	І он *4	Vcc = 3.0 V			_	-1.0	mA
"L" level output current	fout	loL	Vcc = 3.0 V		1.0	_		mA
"H" lovel output current	Doif *8	І дон *4	Vcc = 3.0 V, CS bit = "1"		-8.2	-6.0	-4.1	mA
"H" level output current	Dorf	IDOH .	V _{DOH} = V _{CC} / 2, Ta = +25 °C	CS bit = "0"	-2.2	-1.5	-0.8	mA
"L" level output current	Doif *8	IDOL	$V_{CC} = 3.0 \text{ V},$ $V_{DOL} = V_{CC} / 2,$	CS bit = "1"	4.1	6.0	8.2	mA
5.5. 53.64. 53.1511	Dorf	.502	Ta = +25 °C	CS bit = "0"	0.8	1.5	2.2	mA

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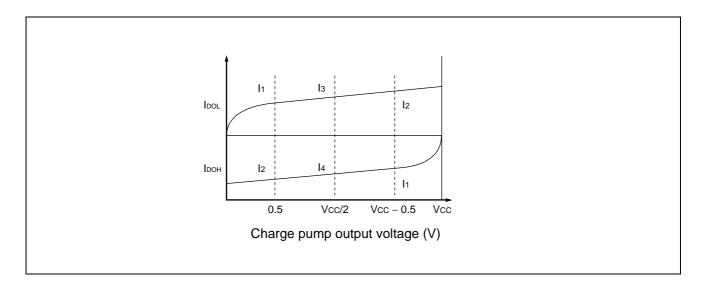
 $(Vcc = 2.7 \text{ V to } 3.6 \text{ V}, Ta = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$

Parameter Sy		Symbol	Condition	Value			Unit
		Syllibol	Condition	Min	Тур	Max	Oilit
	IDOL/IDOH	I DOMТ *5	V _{DO} = V _{CC} / 2	_	3	10	%
Charge pump	vs V _{DO}	DOVD *6	$0.5 \text{ V} \le \text{V}_{\text{DO}} \le \text{V}_{\text{CC}} - 0.5 \text{ V}$	_	10	15	%
current rate	vs Ta	IDOTA *7	$-40 ^{\circ}\text{C} \le \text{Ta} \le 85 ^{\circ}\text{C},$ $V_{DO} = V_{CC} / 2$	—	5	10	%

- *1 : Conditions ; fosc = 12.8 MHz, Ta = +25 °C, SW = "0" in locking state.
- *2 : VccIF = VcCRF = 3.0 V, fosc = 12.8 MHz, Ta = +25 °C, in power saving mode. PSIF = PSRF = GND

 $V_{IH} = V_{CC}$, $V_{IL} = GND$ (at CLK, Data, LE)

- *3 : AC coupling. 1000 pF capacitor is connected under the condition of Min operating frequency.
- *4: The symbol "-" (minus) means the direction of current flow.
- *5 : Vcc = 3.0 V, $Ta = +25 °C (||I_3| |I_4||) / [(|I_3| + |I_4|) / 2] × 100 (%)$
- *6 : Vcc = 3.0 V, $Ta = +25 °C [(||I_2| |I_1||) / 2] / [(|I_1| + |I_2|) / 2] × 100 (%) (Applied to both loot and looh)$
- *7 : Vcc = 3.0 V, [||IDO (+85 °C) | |IDO (-40 °C) || / 2] / [|IDO (+85 °C) | + |IDO (-40 °C) | / 2] × 100 (%) (Applied to both IDOL and IDOH)
- *8 : When Charge pump current is measured, set LDS = "0", T1 = "0" and T2 = "1".



■ FUNCTIONAL DESCRIPTION

1. Pulse swallow function

 $f_{VCO} = [(P \times N) + A] \times f_{OSC} \div R$

fvco: Output frequency of external voltage controlled oscillator (VCO)

P : Preset divide ratio of dual modulus prescaler (32 or 64 for IF-PLL, 64or 128 for RF-PLL)

N : Preset divide ratio of binary 11-bit programmable counter (3 to 2,047) A : Preset divide ratio of binary 7-bit swallow counter ($0 \le A \le 127$, A < N)

fosc: Reference oscillation frequency (OSCIN input frequency)

R : Preset divide ratio of binary 14-bit programmable reference counter (3 to 16,383)

2. Serial Data Input

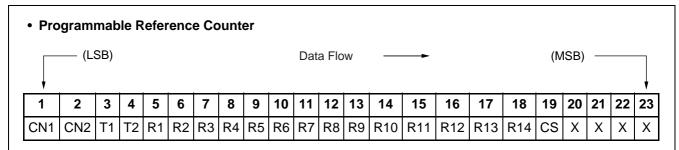
The serial data is entered using three pins, Data pin, Clock pin, and LE pin. Programmable dividers of IF/RF-PLL sections, programmable reference dividers of IF/RF-PLL sections are controlled individually.

The serial data of binary data is entered through Data pin.

On rising edge of Clock, one bit of the serial data is transferred into the shift register. On a rising edge of load enable signal, the data stored in the shift register is transferred to one of latches depending upon the control bit data setting.

	The programmable reference counter for the IF-PLL	The programmable reference counter for the RF-PLL	The programmable counter and the swallow counter for the IF-PLL	The programmable counter and the swallow counter for the RF-PLL	
CN1	0	1	0	1	
CN2	0	0	1	1	

(1) Shift Register Configuration



CS : Charge pump current select bit

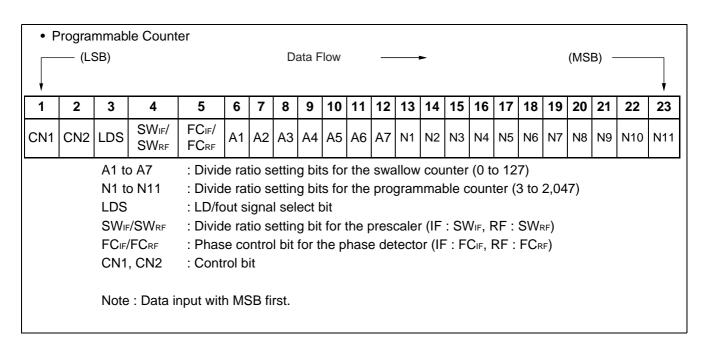
R1 to R14 : Divide ratio setting bits for the programmable reference counter (3 to 16,383)

T1, T2 : LD/fout output setting bit

CN1, CN2 : Control bit

X : Dummy bits (Set "0" or "1")

Note: Data input with MSB first.



(2) Data setting

• Binary 14-bit Programmable Reference Counter Data Setting

Divide ratio	R14	R13	R12	R11	R10	R9	R8	R7	R6	R5	R4	R3	R2	R1
3	0	0	0	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited.

Binary 11-bit Programmable Counter Data Setting

Divide ratio	N11	N10	N9	N8	N7	N6	N5	N4	N3	N2	N1
3	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•	•	•
2047	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited

Binary 7-bit Swallow Counter Data Setting

Divide ratio	A7	A6	A5	A4	А3	A2	A 1
0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	1
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
127	1	1	1	1	1	1	1

• Prescaler Data Setting

Divide ratio	SW = "1"	SW = "0"
Prescaler divide ratio IF-PLL	32/33	64/65
Prescaler divide ratio RF-PLL	64/65	128/129

• Charge Pump Current Setting

Current value	CS
±6.0 mA	1
±1.5 mA	0

• LD/fout output Selectable Bit Setting

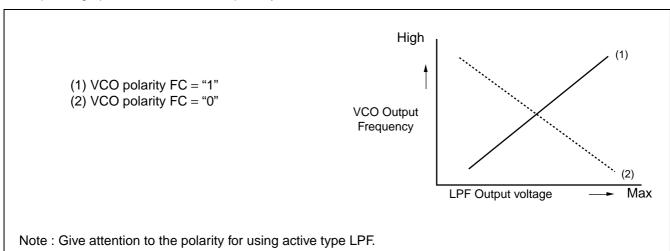
LD/fout	pin state	LDS	T1	T2
		0	0	0
LD o	output	0	1	0
		0	1	1
	frıғ	1	0	0
fout	fr _{RF}	1	1	0
output	fpı⊧	1	0	1
	fpref	1	1	1

• Phase Comparator Phase Switching Data Setting

Phase comparator input	FCIF, RF = "1"	FCIF, RF = "0"
	Doif, Dorf	Doif, Dorf
fr > fp	Н	L
fr < fp	L	Н
fr = fp	Z	Z

Z : High-impedance

Depending upon the VCO and LPF polarity, FC bit should be set.



3. Power Saving Mode (Intermittent Mode Control Circuit)

Status	PS pin
Normal mode	Н
Power saving mode	L

The intermittent mode control circuit reduces the PLL power consumption.

By setting the PS pin low, the device enters into the power saving mode, reducing the current consumption. See the Electrical Characteristics chart for the specific value.

The phase detector output, Do, becomes high impedance.

For the dual PLL, the lock detector, LD, is as shown in the LD Output Logic table.

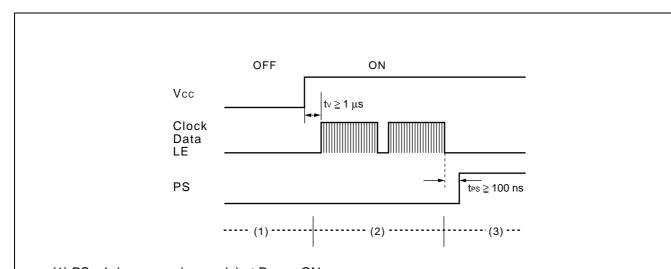
Setting the PS pin high, releases the power saving mode, and the device works normally.

The intermittent mode control circuit also ensures a smooth startup when the device returns to normal operation. When the PLL is returned to normal operation, the phase comparator output signal is unpredictable. This is because of the unknown relationship between the comparison frequency (fp) and the reference frequency (fr) which can cause a major change in the comparaor output, resulting in a VCO frequency jump and an increase in lockup time.

To prevent a major VCO frequency jump, the intermittent mode control circuit limits the magnitude of the error signal from the phase detector when it returns to normal operation.

Notes: • When power (VCC) is first applied, the device must be in standby mode.

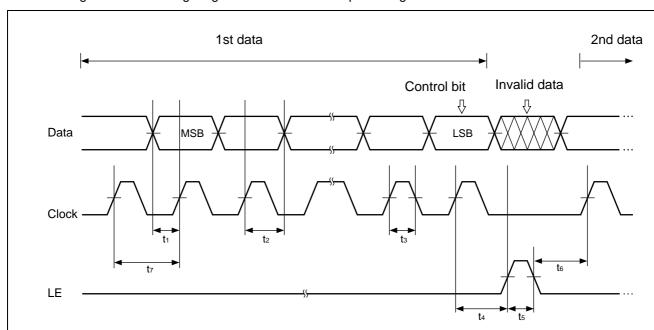
• PS pin must be set "L" at Power-ON.



- (1) PS = L (power saving mode) at Power-ON
- (2) Set serial data at least 1 μ s after the power supply becomes stable ($Vcc \ge 2.2 \text{ V}$).
- (3) Release power saving mode (PS_{IF}, PS_{RF}: "L" \rightarrow "H") at least 100 ns later after setting serial data.

4. Serial Data Data Input Timing

Divide ratio is performed through a serial interface using the Data pin, Clock pin, and LE pin. Setting data is read into the shift register at the rise of the Clock signal, and transferred to a latch at the rise of the LE signal. The following diagram shows the data input timing.

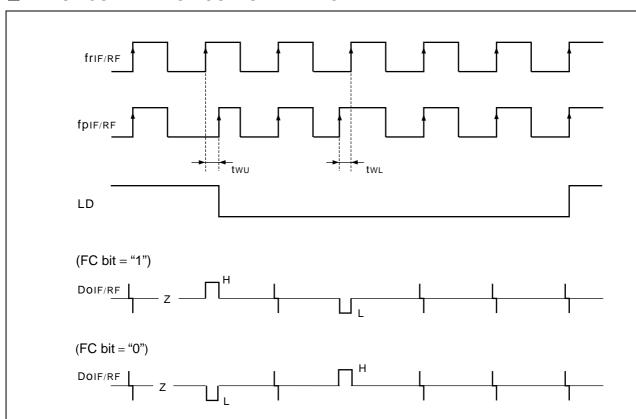


Parameter	Min	Тур	Max	Unit
t ₁	20		_	ns
t 2	20	_	_	ns
tз	30		_	ns
t ₄	30	_		ns

Parameter	Min	Тур	Max	Unit
t 5	100	_	_	ns
t 6	20			ns
t ₇	100	_		ns

Note: LE should be "L" when the data is transferred into the shift register.

■ PHASE COMPARATOR OUTPUT WAVEFORM



• LD Output Logic

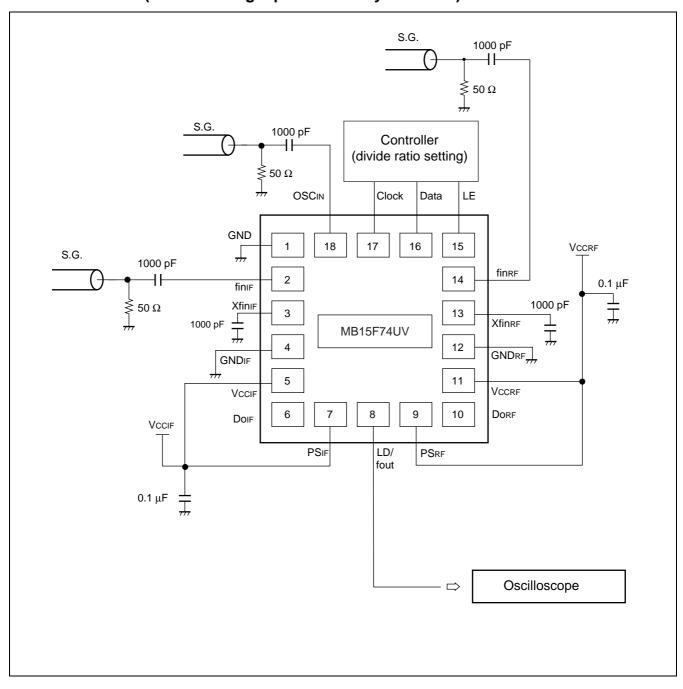
IF-PLL section	RF-PLL section	LD output
Locking state/Power saving state	Locking state/Power saving state	Н
Locking state/Power saving state	Unlocking state	L
Unlocking state	Locking state/Power saving state	L
Unlocking state	Unlocking state	L

Notes : • Phase error detection range = -2π to $+2\pi$

- Pulses on DoiF/RF signals during locking state are output to prevent dead zone.
- LD output becomes low when phase error is two or more.
- LD output becomes high when phase error is twl or less and continues to be so for three cycles or more.
- two and twL depend on OSCIN input frequency as follows.

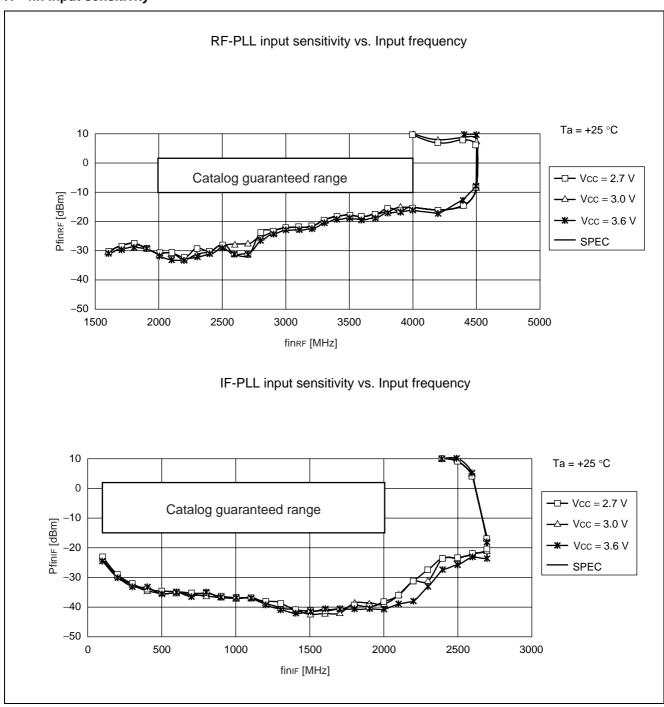
 $t_{WU} \ge 2/fosc$: e.g. $t_{WU} \ge 156.3$ ns when fosc = 12.8 MHz $t_{WU} \le 4/fosc$: e.g. $t_{WL} \le 312.5$ ns when fosc = 12.8 MHz

■ TEST CIRCUIT (for Measuring Input Sensitivity fin/OSC_{IN})

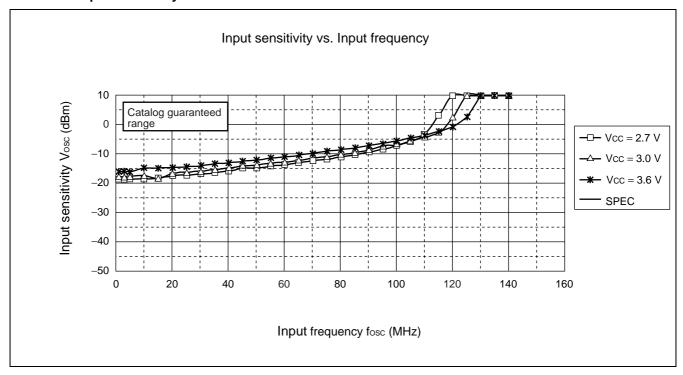


■ TYPICAL CHARACTERISTICS

1. fin input sensitivity



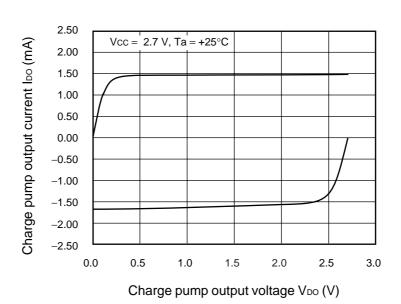
2. OSC_{IN} input sensitivity



3. RF/IF-PLL Do output current

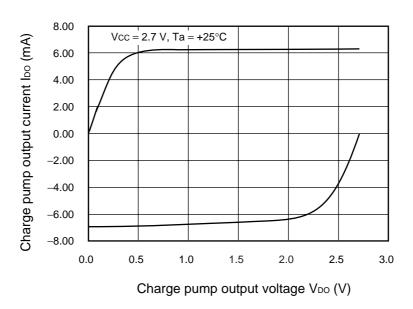




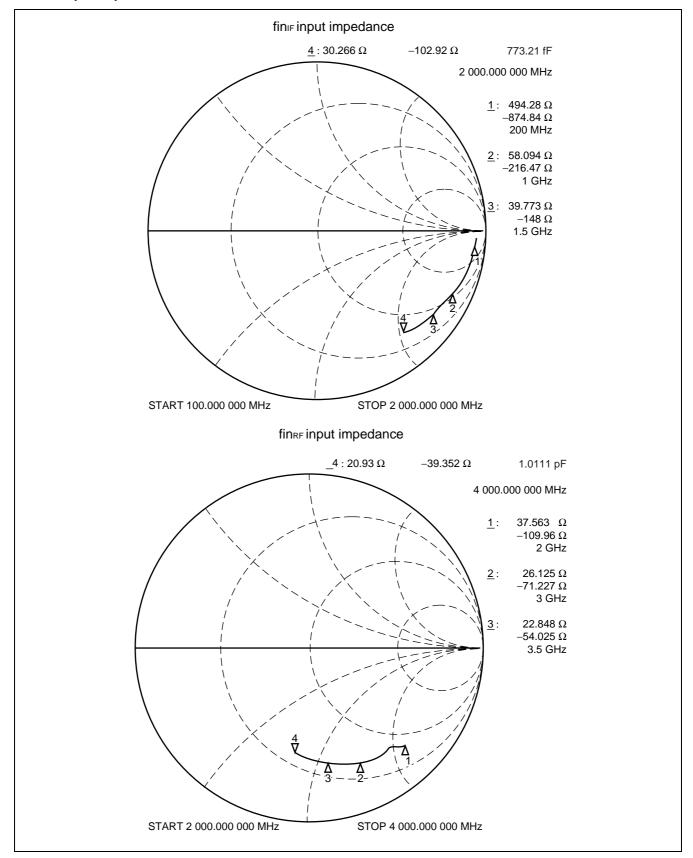


• 6.0 mA mode

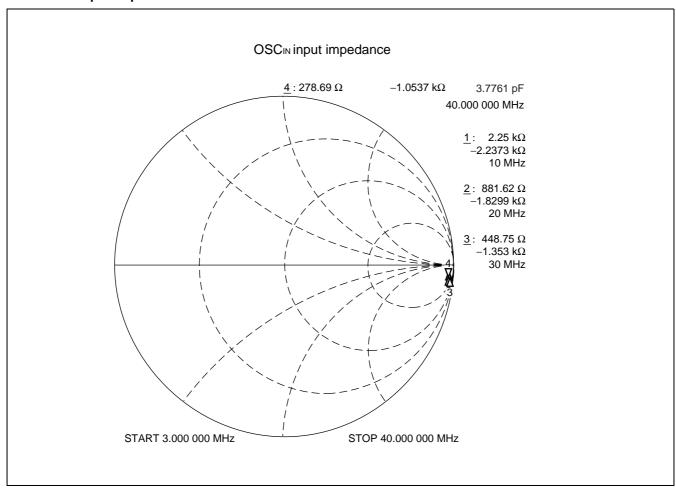
$$I_{DO} - V_{DO}$$



4. fin input impedance

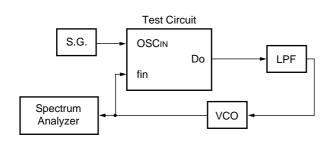


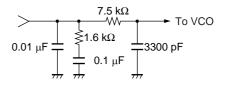
5. OSC_{IN} input impedance



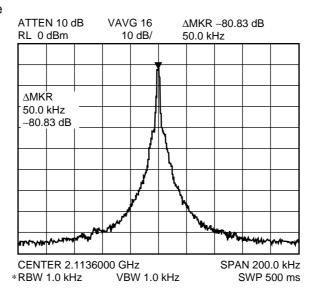
■ REFERENCE INFORMATION

(for Lock-up Time, Phase Noise and Reference Leakage)

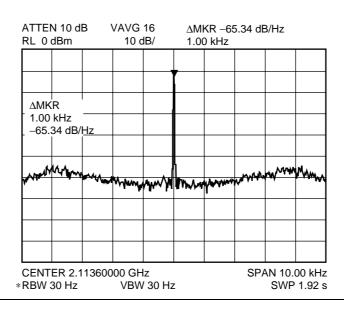




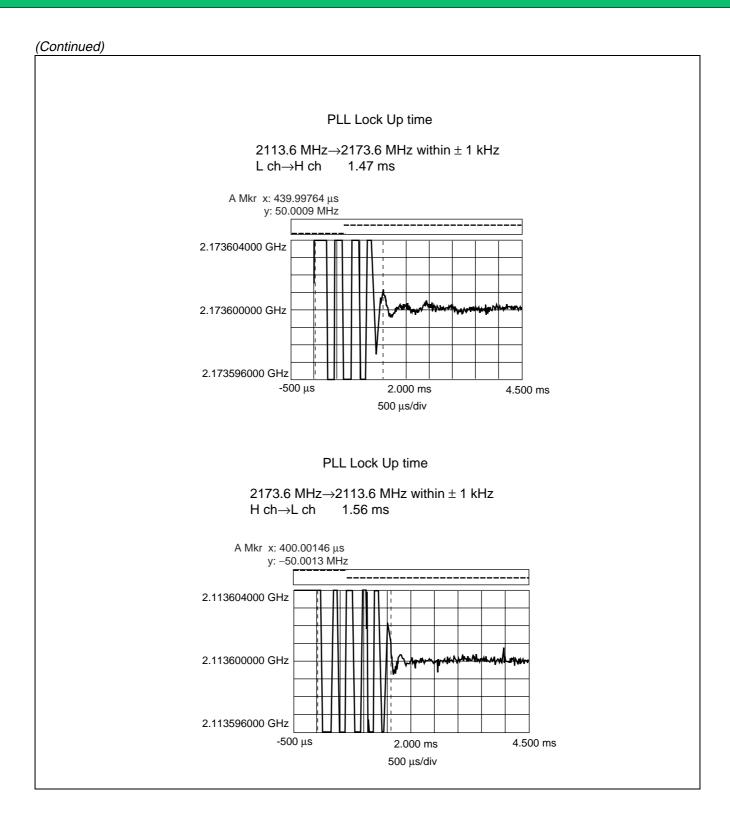
• PLL Reference Leakage



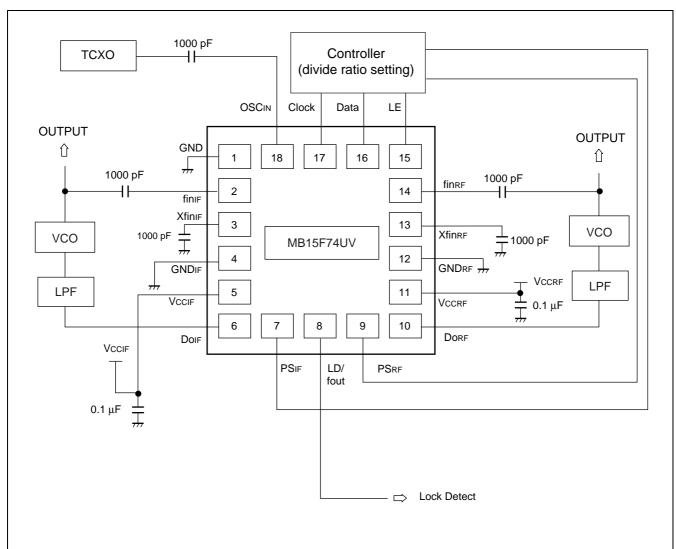
• PLL Phase Noise



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■ APPLICATION EXAMPLE



Note: Clock, Data, LE: The schmitt trigger circuit is provided (insert a pull-down or pull-up registor to prevent oscillation when open-circuit in the input).

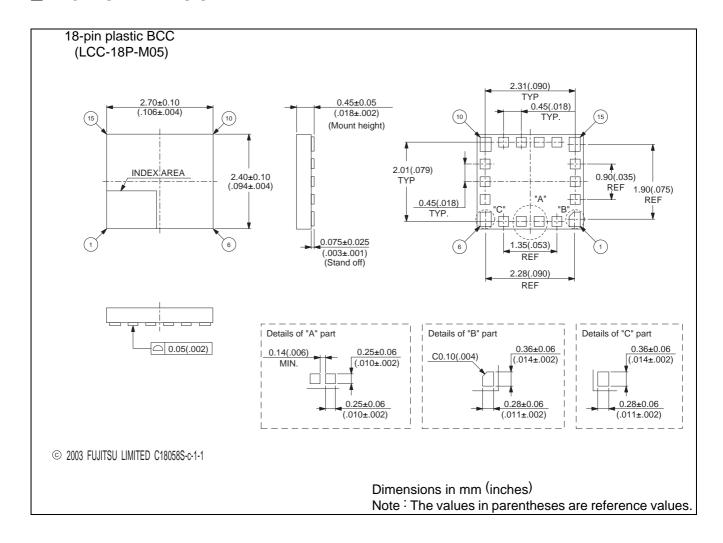
■ USAGE PRECAUTIONS

- (1) VCCRF and VCCIF must be equal voltage.
 - Even if either RF-PLL or IF-PLL is not used, power must be supplied to VccrF and VccrF to keep them equal. It is recommended that the non-use PLL is controlled by power saving function.
- (2) To protect against damage by electrostatic discharge, note the following handling precautions:
 - Store and transport devices in conductive containers.
 - Use properly grounded workstations, tools, and equipment.
 - Turn off power before inserting or removing this device into or from a socket.
 - Protect leads with conductive sheet, when transporting a board mounted device

■ ORDERING INFORMATION

Part number	Package	Remarks
MB15F74UVPVB	18-pin plastic BCC (LCC-18P-M05)	

■ PACKAGE DIMENSION



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